

Attorney's Docket No.: HIRA-0230

DECLARATION, POWER OF ATTORNEY AND PETITION

I (We), the undersigned inventor(s), hereby declare that:

My residence, post office address and citizenship are as stated below next to my name, I (We) believe that I am (we are) the original, first, and joint (sole) inventor(s) of the subject matter which is claimed and for which a patent is sought on the invention entitled HYDROGEN OR HELIUM PERMEATION MEMBRANE AND STORAGE
MEMBRANE AND PROCESS FOR PRODUCING THE SAME

the specification of which

- is attached hereto.
- was filed on _____ as
Application Serial No. _____
and amended on _____
- was filed as PCT international application
Number PCT/JP2005/000001
on January 4, 2005
and was amended under PCT Article 19
on _____ (if applicable).

I (We) hereby state that I (We) have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above; that I (We) do not know and do not believe that this invention was ever known or used before my invention or discovery thereof, or patented or described in any printed publication in any country before my invention or discovery thereof, or more than one year prior to this application, or in public use or on sale in the United States for more than one year prior to this application; that this invention or discovery has not been patented or made the subject of an inventor's certificate in any country foreign to the United States on an application filed by me or my legal representatives or assigns more than twelve months before this application.

I (We) acknowledge the duty to disclose information known to be material to the patentability of this application as defined in Section 1.56 of Title 37 Code of Federal Regulations.

I (We) hereby claim foreign priority benefits under Section 119(a)-(d) of Title 35 United States Code, of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Application No.	Country	Filing date	Priority claimed
<u>2004-038997</u>	<u>Japan</u>	<u>January 15, 2004</u>	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
_____	_____	_____	<input type="checkbox"/> Yes <input type="checkbox"/> No
_____	_____	_____	<input type="checkbox"/> Yes <input type="checkbox"/> No
_____	_____	_____	<input type="checkbox"/> Yes <input type="checkbox"/> No

I hereby claim the benefit under Section 119(e) of Title 35 United States Code, of any United States application(s) listed below.

(Application Number)

(Filing Date)

(Application Number)

(Filing Date)

I (We) hereby claim the benefit under Section 120 of Title 35 United States Code, of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Section 112 of Title 35 United States Code, I (We) acknowledge the duty to disclose material information as defined in Section 1.56(a) of Title 37 Code of Federal Regulations, which occurred between the filing date of the prior application and national or PCT international filing date of this application:

Application Serial No.	Filing Date	Status (pending, patented, abandoned)
_____	_____	_____
_____	_____	_____
_____	_____	_____

And I (We) hereby appoint: Stanley P. Fisher, Registration No. 24,344 and Juan Carlos Marquez, Registration No. 34,072.

I(We) hereby request that all correspondence regarding this application be sent to the firm of Reed Smith LLP whose Post office address is: 3110 Fairview Park Drive, Suite 1400, Falls Church, Virginia 22042-4503 U.S.A.

I (We) declare further that all statements made herein of my (our) knowledge are true and that all statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Shinichi IKEDA

NAME OF FIRST INVENTOR

Shinichi Ikeda

Signature of Inventor

June 26, 2006

Date

Residence: Ibaraki, Japan

Citizen of: Japan

Post Office Address: c/o Tsukuba Center,

National Institute of Advanced

Industrial Science and Technology,

1-1, Higashi 1-chome, Tsukuba-shi,

Ibaraki 305-8561 Japan

Norio UMEYAMA

NAME OF SECOND INVENTOR

Norio Umeysama

Signature of Inventor

June 26, 2006

Date

Residence: Ibaraki, JapanCitizen of: JapanPost Office Address: c/o Tsukuba Center, National Institute of Advanced Industrial Science and Technology, 1-1, Higashi 1-chome, Tsukuba-shi, Ibaraki 305-8561 JapanAriyoshi OGASAWARA

NAME OF THIRD INVENTOR

Ariyoshi Ogawara

Signature of Inventor

June 26, 2006

Date

Residence: Kanagawa, JapanCitizen of: JapanPost Office Address: c/o SFC CO., LTD., 11, Nihon-ohdohri, Naka-ku, Yokohama-shi, Kanagawa 231-0021 JapanHideo ABE

NAME OF FOURTH INVENTOR

Hideo Abe

Signature of Inventor

June 26, 2006

Date

Residence: Kanagawa, JapanCitizen of: JapanPost Office Address: c/o Techno-center Dept., SFC CO., LTD., Room 106, Leading Venture Plaza, 75-1, Ono-machi, Tsurumi-ku, Yokohama-shi, Kanagawa 230-0046 Japan

Yasuhito TANAKA

NAME OF FIFTH INVENTOR

Yasuhito Tanaka

Signature of Inventor

June 26, 2006

Date

Residence: Kanagawa, Japan

Citizen of: Japan

Post Office Address: _____

c/o Techno-center Dept., SFC CO., LTD.,
Room 106, Leading Venture Plaza, 75-1,
Ono-machi, Tsurumi-ku, Yokohama-shi,
Kanagawa 230-0046 Japan

NAME OF SIXTH INVENTOR

Signature of Inventor

Date

Residence: _____

Citizen of: _____

Post Office Address: _____

NAME OF SEVENTH INVENTOR

Signature of Inventor

Date

Residence: _____

Citizen of: _____

Post Office Address: _____

Attorney's Docket No.: HIRA.0230
Assignment of Application

WHEREAS, I (WE) _____
Shinichi IKEDA, Norio UMEYAMA of
both c/o Tsukuba Center, National Institute of Advanced Industrial Science and Technology,
1-1, Higashi 1-chome, Tsukuba-shi, Ibaraki 305-8561 Japan,
Ariyoshi OGASAWARA of c/o SFC CO., LTD., 11, Nihon-ohdohri, Naka-ku,
Yokohama-shi, Kanagawa 231-0021 Japan,
Hideo ABE, Yasuhito TANAKA of
both c/o Techno-center Dept., SFC CO., LTD., Room 106, Leading Venture Plaza,
75-1, Ono-machi, Tsurumi-ku, Yokohama-shi, Kanagawa 230-0046 Japan

,respectively,
have invented certain new and useful improvements in: _____
HYDROGEN OR HELIUM PERMEATION MEMBRANE AND STORAGE
MEMBRANE AND PROCESS FOR PRODUCING THE SAME
for which an application for Letters Patent was executed on June 26, 2006
(Application No. _____, filed _____), and

WHEREAS, SFC CO., LTD.
(hereinafter referred to as "ASSIGNEE") having a place of business at: ____
11, Nihon-ohdohri, Naka-ku, Yokohama-shi, Kanagawa 231-0021 Japan
is desirous of acquiring the entire right, title and interest in and to said
invention and in and to any Letters Patent that may be granted therefore in the
United States and its territorial possessions and in any and all foreign countries;

NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), the receipt whereof is hereby acknowledged, and for other good and valuable consideration, I (WE), by these presents do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof.

I (WE) hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any official of any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my (our) entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me (us) had this Assignment and sale not been made.

Further, I (WE) agree that I (WE) will communicate to said ASSIGNEE or its legal representatives and assigns covenant and any facts known to me (us) respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letter Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

The undersigned hereby grant(s) the firm of Reed Smith LLP of 3110 Fairview Park Drive, Suite 1400, Falls Church, Virginia 22042-4503 U.S.A. the power to insert on this assignment any further identification, including the application number and filing date, which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: June 26, 2006

Shinichi Ikeda

(Signature of inventor) Shinichi IKEDA

Date: June 26, 2006

Norio Umeyama

(Signature of inventor) Norio UMEYAMA

Date: June 26, 2006

Ariyoshi Ogasawara
(Signature of inventor) Ariyoshi OGASAWARA

Date: June 26, 2006

Hideo ABE
(Signature of inventor) Hideo ABE

Date: June 26, 2006

Yasuhito Tanaka
(Signature of inventor) Yasuhito TANAKA